

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HISATO OSAWA	12/19/2019
ATSUSHI NISHIMURA	12/20/2019
KENJI NAKANO	12/19/2019
RECEIVING PARTY DATA	
Name:	YAMABIKO CORPORATION
Street Address:	7-2, SUEHIROCHO 1-CHOME
City:	TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16742261
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NAME OF SUBMITTER:	BRITTANY NANZIG
SIGNATURE:	/Brittany Nanzig/
DATE SIGNED:	01/15/2020
Total Attachments: 3	
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source=ISO-YC0002USU1_20200110_Assignment#page3.tif	

ASSIGNMENT

WHEREAS, we,

Hisato OSAWA, residing in **Japan**, with a mailing address of

c/o Yamabiko Corporation, 7-2, Suehirocho 1-chome, Ohme-shi, Tokyo 1988760, Japan;

Atsushi NISHIMURA, residing in **Japan**, with a mailing address of

c/o Yamabiko Corporation, 7-2, Suehirocho 1-chome, Ohme-shi, Tokyo 1988760, Japan; and

Kenji NAKANO, residing in **Japan**, with a mailing address of

c/o Yamabiko Corporation, 7-2, Suehirocho 1-chome, Ohme-shi, Tokyo 1988760, Japan;

(hereinafter "Assignors," "we" or "us"), made certain new and useful inventions and improvements, those are the subject of an application for Letters Patent of the United States, titled

ELECTRIC-POWER-DRIVEN WORKING DEVICE

(identified as application Serial No. 16/742,461 filed on January 14, 2020 (hereinafter "Application"));

AND WHEREAS, **Yamabiko Corporation**, a corporation organized and existing under and by virtue of the laws of **Japan**, and having an office and place of business at **7-2, Suehirocho 1-chome, Ohme-shi, Tokyo 1988760, Japan** (hereinafter "Assignee"), is desirous of acquiring the entire right, title, and interest in and to said inventions, improvements, and Application and in and to the Letters Patent(s) to be obtained therefor;

NOW THEREFORE, to all whom it may concern, be it known that for good and valuable considerations, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign, and transfer unto said Assignee, its successors, or its assigns, the entire right, title, and interest for all countries in and to the aforesaid Application, and all inventions and improvements disclosed therein, and in and to the Application, all non-provisionals, divisions, continuations, or renewals thereof, all Letters Patent(s) that may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications that have been or shall be filed in any foreign countries for Letters Patent(s) on the inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent(s) of foreign countries that may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent(s) for the aforesaid inventions and improvements to the Assignee as the assignee of the entire right, title, and interest in and to the same, for the use of the Assignee, its successors and assigns. Additionally, we hereby assign all other rights, title, and interest in ideas, plans, software code, materials, written matter,

images, models, prototypes, data, or other creative materials prepared for Assignee that may result in intellectual property rights such as, but not limited to, trademarks, copyrights, trade secrets, or otherwise. The foregoing assignment includes, without limitation, the right to sue for past, present, and future infringement of the aforesaid Application, all Letters Patent(s) that may be granted therefrom, and all other intellectual property rights, and the right to collect and receive any damages, royalties, or settlement for such past, present, and future infringements and any and all causes of action relating to any of the inventions or discoveries described in the aforesaid Application, all Letters Patent(s) that may be granted therefrom, and all other intellectual property rights.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute, and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments, and other documents, and will communicate to said Assignee, its successors, and its representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things that may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors, or its assigns the entire right, title, and interest in and to the improvements, inventions, Application, Letters Patent(s), rights, titles, benefits, privileges, and advantages hereby sold, assigned, and conveyed, or intended so to be.

AND, furthermore, we covenant and agree with said Assignee, its successors, and its assigns, that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

[SIGNATURE PAGE FOLLOWS]

IN TESTIMONY WHEREOF, I have hereunto set my hand on December 19, 2019
Date

大澤久人
Hisato OSAWA

IN TESTIMONY WHEREOF, I have hereunto set my hand on December 20, 2019
Date

西村 篤
Atsushi NISHIMURA

IN TESTIMONY WHEREOF, I have hereunto set my hand on December 19, 2019
Date

Kenji N
Kenji NAKANO